

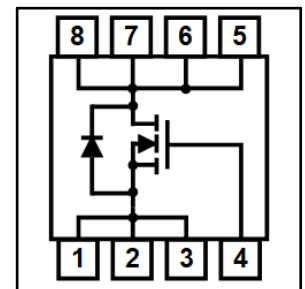
Automotive MOSFET

OptiMOS™ 7 Power-Transistor



Features

- OptiMOS™ power MOSFET for automotive applications
- N-channel – Enhancement mode – Normal Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- RoHS compliant
- 100% Avalanche tested



Potential Applications

General automotive applications.

Product Validation

Qualified for automotive applications. Product validation according to AEC-Q101.

Product Summary

V_{DS}	80	V
$R_{DS(on)}$	2.4	mΩ
I_D (chip limited)	165	A

Type	Package	Marking
IAUCN08S7N024	PG-TDSON-8-34	7N08N024

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Maximum Ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$V_{GS} = 10\text{ V}$, Chip limitation ^{1,2)}	165	A
		$V_{GS} = 10\text{ V}$, DC current	150	
		$T_a = 100^\circ\text{C}$, $V_{GS} = 10\text{ V}$, R_{thJA} on 2s2p ^{2,3)}	23	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C = 25^\circ\text{C}$, $t_p = 100\ \mu\text{s}$	481	
Avalanche energy, single pulse ²⁾	E_{AS}	$I_D = 55\text{ A}$	103	mJ
Avalanche current, single pulse	I_{AS}	–	110	A
Gate source voltage	V_{GS}	–	± 20	V
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$	148	W
Operating and storage temperature	T_j, T_{stg}	–	-55 ... +175	$^\circ\text{C}$

Thermal Characteristics²⁾

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	–	–	–	1.0	K/W
Thermal resistance, junction - ambient ³⁾	R_{thJA}	–	–	25.9	–	

Electrical Characteristics

 at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Static Characteristics

Drain-source breakdown voltage	$V_{(Br)DSS}$	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	80	–	–	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 71\text{ }\mu\text{A}$	2.3	2.8	3.2	
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 80\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 25\text{ °C}$	–	–	1	μA
		$V_{DS} = 80\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 100\text{ °C}^{2)}$	–	–	18	
Gate-source leakage current	I_{GSS}	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$	–	–	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 7\text{ V}$, $I_D = 38\text{ A}$	–	2.5	2.9	m Ω
		$V_{GS} = 10\text{ V}$, $I_D = 75\text{ A}$	–	2.2	2.4	
Gate resistance ²⁾	R_G	–	–	1.2	–	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics²⁾						
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 40\text{ V}, f = 1\text{ MHz}$	-	3528	4586	pF
Output capacitance	C_{oss}		-	1433	1863	
Reverse transfer capacitance	C_{rss}		-	19	28	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 40\text{ V}, V_{GS} = 10\text{ V}, I_D = 75\text{ A}, R_G = 3.5\ \Omega$	-	14	-	ns
Rise time	t_r		-	14	-	
Turn-off delay time	$t_{d(off)}$		-	26	-	
Fall time	t_f		-	17	-	

Gate Charge Characteristics²⁾

Gate to source charge	Q_{gs}	$V_{DD} = 40\text{ V}, I_D = 75\text{ A}, V_{GS} = 0\text{ to }10\text{ V}$	-	16.5	21.5	nC
Gate to drain charge	Q_{gd}		-	9.9	14.9	
Gate charge total	Q_g		-	51.5	67.0	
Gate plateau voltage	$V_{plateau}$		-	4.7	-	V

Reverse Diode

Diode continuous forward current ²⁾	I_S	$T_C = 25^\circ\text{C}$	-	-	150	A
Diode pulse current ²⁾	$I_{S,pulse}$	$T_C = 25^\circ\text{C}, t_p = 100\ \mu\text{s}$	-	-	481	
Diode forward voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_F = 75\text{ A}, T_j = 25^\circ\text{C}$	-	0.9	1.0	V
Reverse recovery time ²⁾	t_{rr}	$V_R = 40\text{ V}, I_F = 50\text{ A}, di_F/dt = 100\text{ A}/\mu\text{s}$	-	34	51	ns
Reverse recovery charge ²⁾	Q_{rr}		-	22	44	nC

¹⁾ Practically the current is limited by the overall system design including the customer-specific PCB.

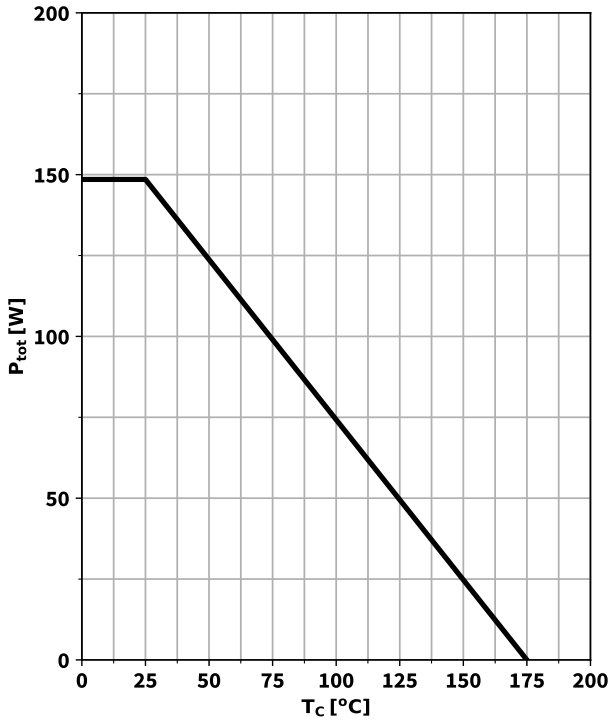
²⁾ The parameter is not subject to production testing – specified by design.

³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

Electrical characteristics diagrams

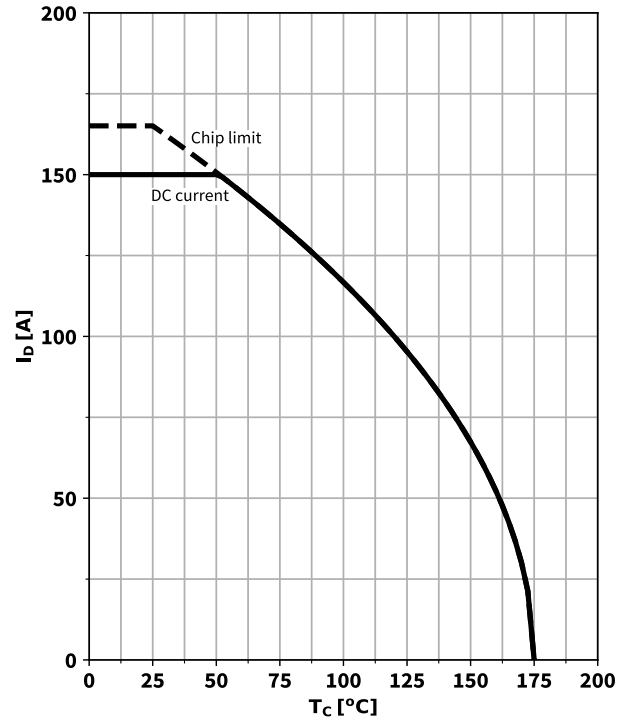
1 Power dissipation

$$P_{tot} = f(T_C); V_{GS} \geq 6V$$



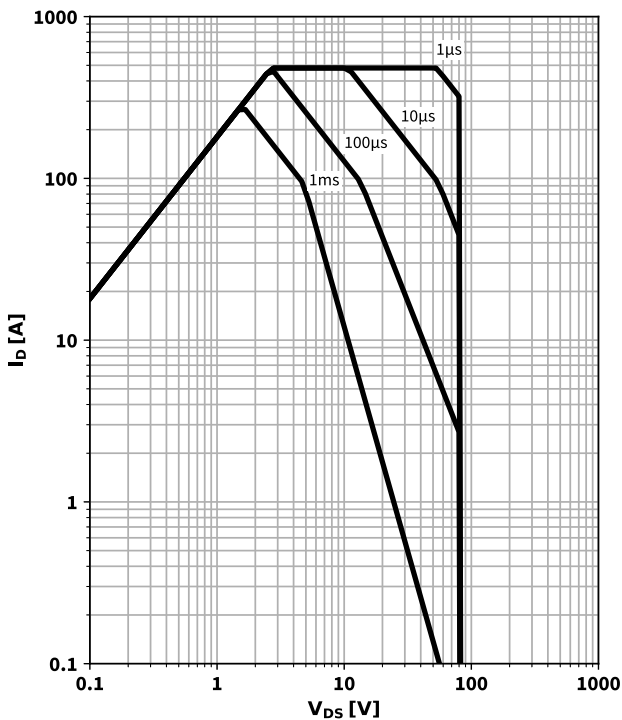
2 Drain current

$$I_D = f(T_C); V_{GS} \geq 6V$$



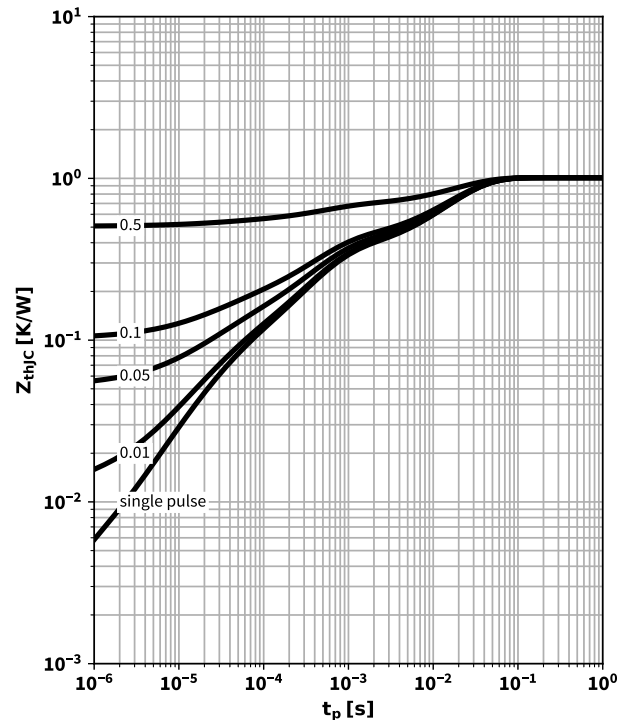
3 Safe operating area

$$I_D = f(V_{DS}); T_C = 25^\circ C; D = 0; \text{parameter: } t_p$$



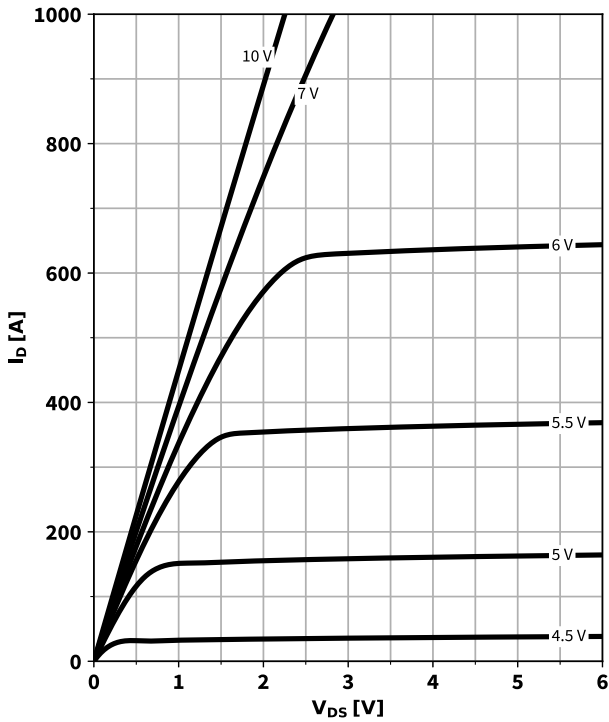
4 Max. transient thermal impedance

$$Z_{thJC} = f(t_p); \text{parameter: } D = t_p/T$$



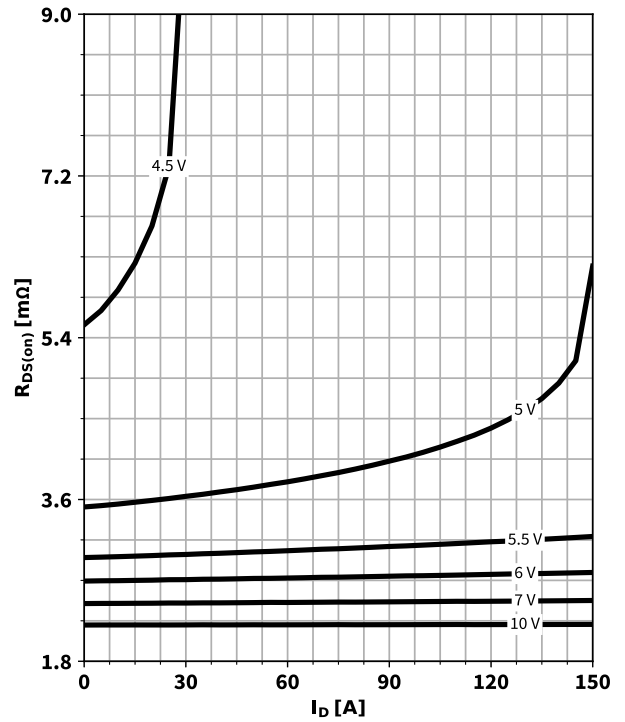
5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ °C};$ parameter: V_{GS}



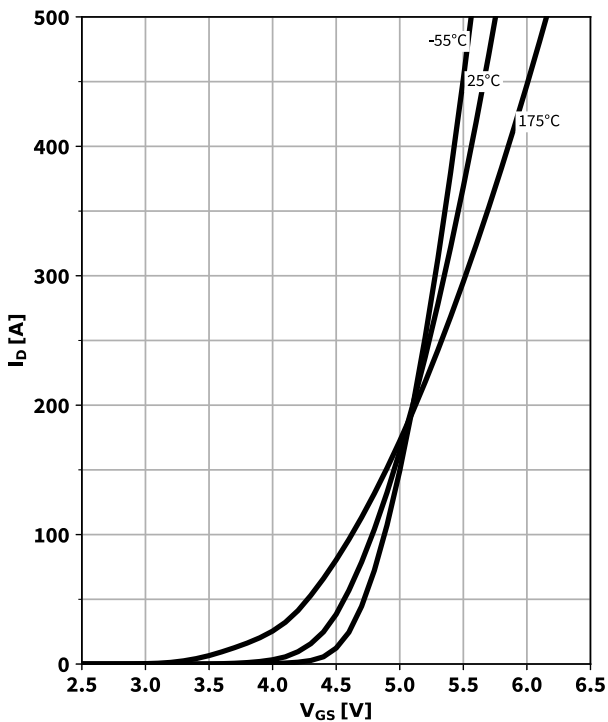
6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D); T_j = 25\text{ °C};$ parameter: V_{GS}



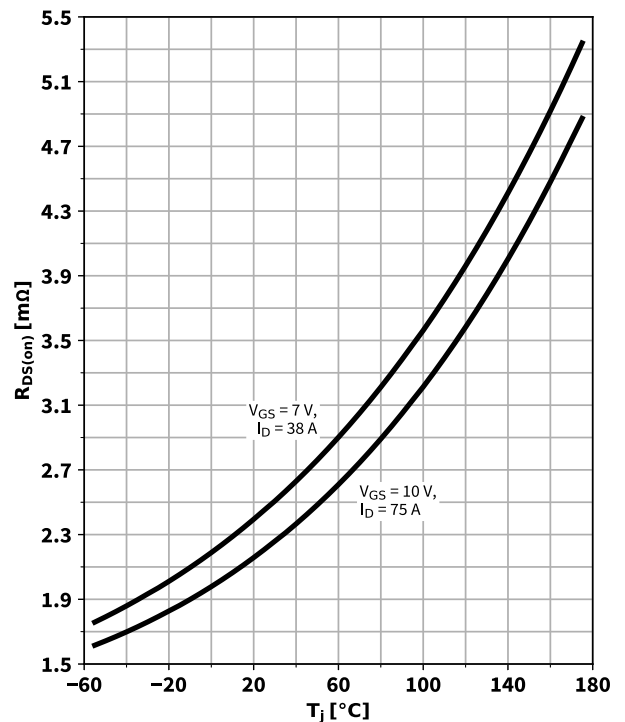
7 Typ. transfer characteristics

$I_D = f(V_{GS}); V_{DS} = 6\text{ V};$ parameter: T_j



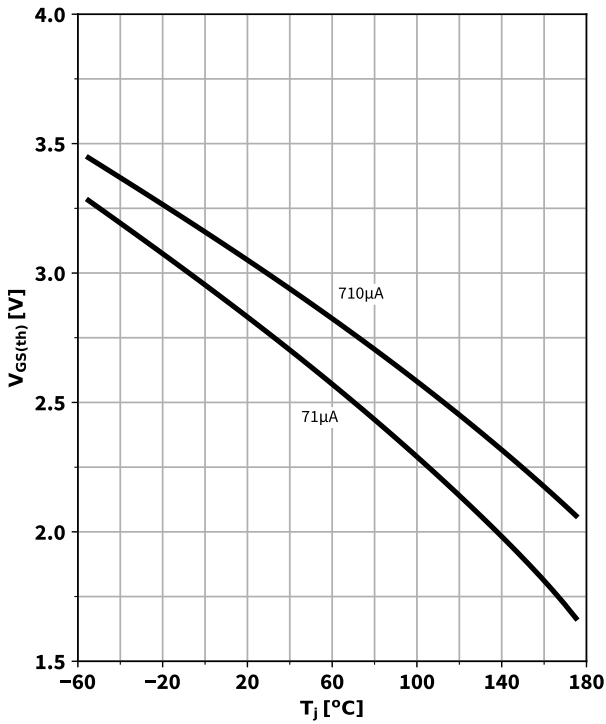
8 Typ. drain-source on-state resistance

$R_{DS(on)} = f(T_j);$ parameter: I_D, V_{GS}



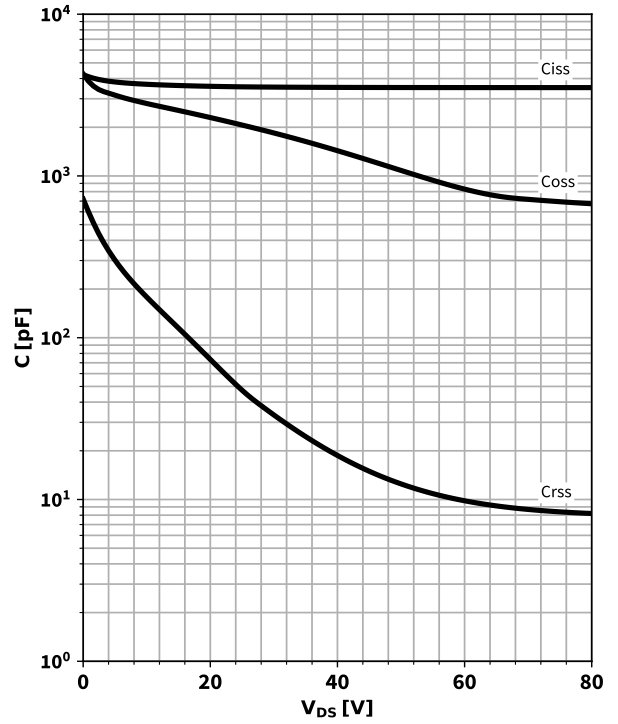
9 Typ. gate threshold voltage

$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$; parameter: I_D



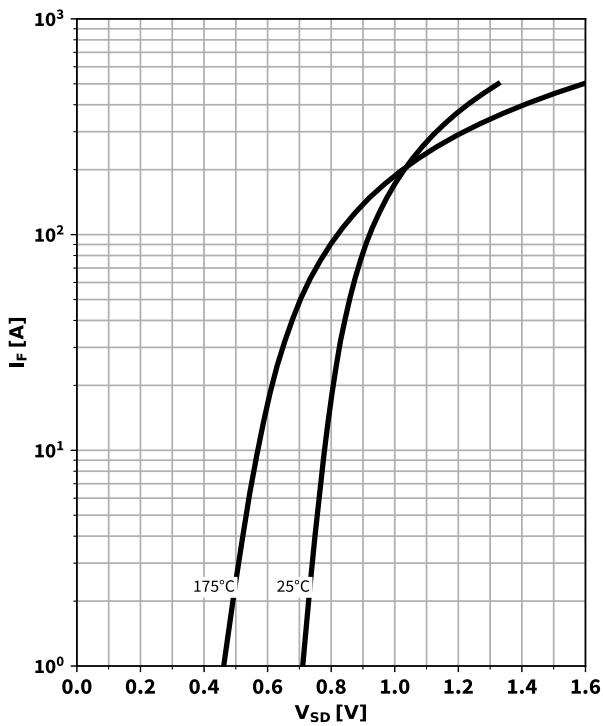
10 Typ. capacitances

$C = f(V_{DS})$; $V_{GS} = 0 V$; $f = 1 MHz$



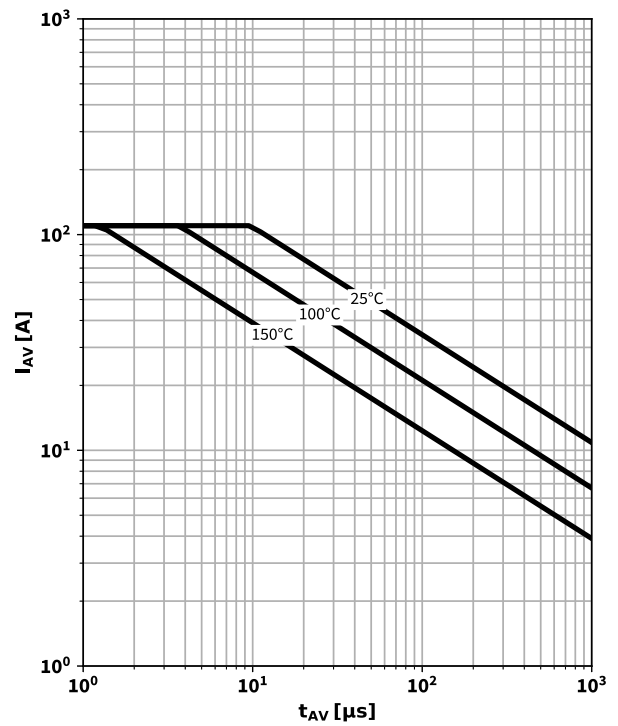
11 Typ. forward diode characteristics

$I_F = f(V_{SD})$; parameter: T_j



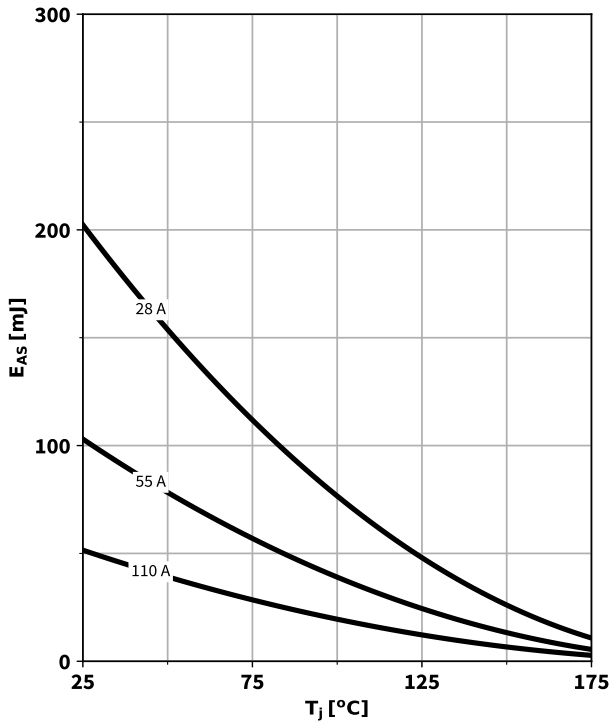
12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$; parameter: $T_{j(start)}$



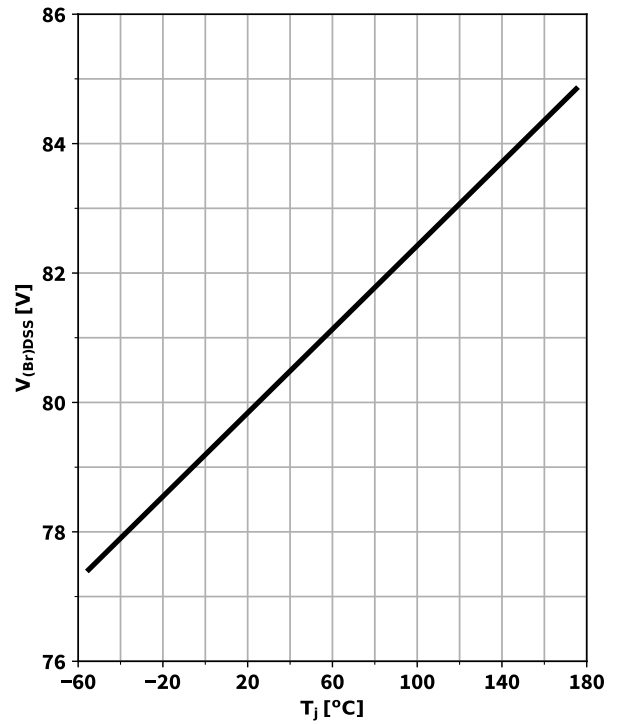
13 Typical avalanche energy

$E_{AS} = f(T_j)$; parameter: I_D



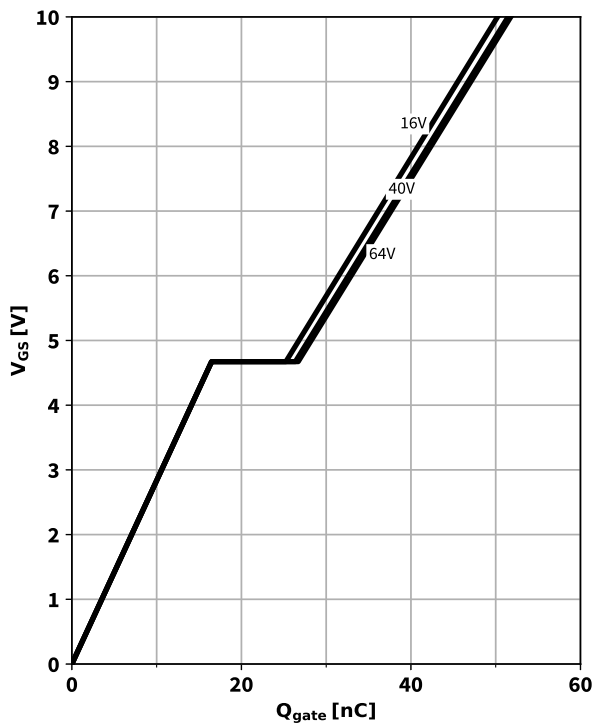
14 Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$; $I_D = 1 \text{ mA}$

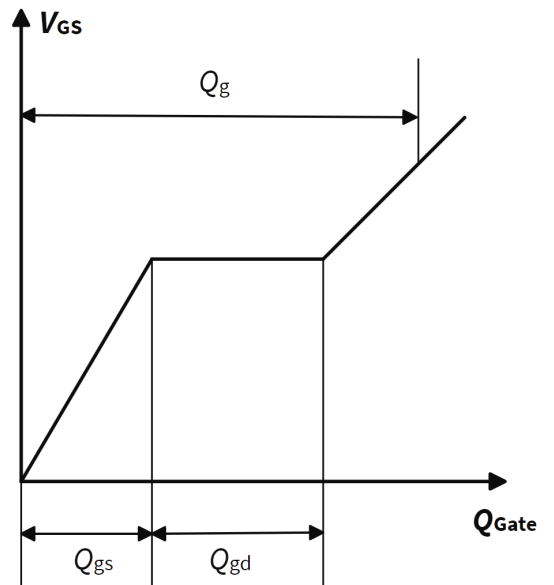


15 Typ. gate charge

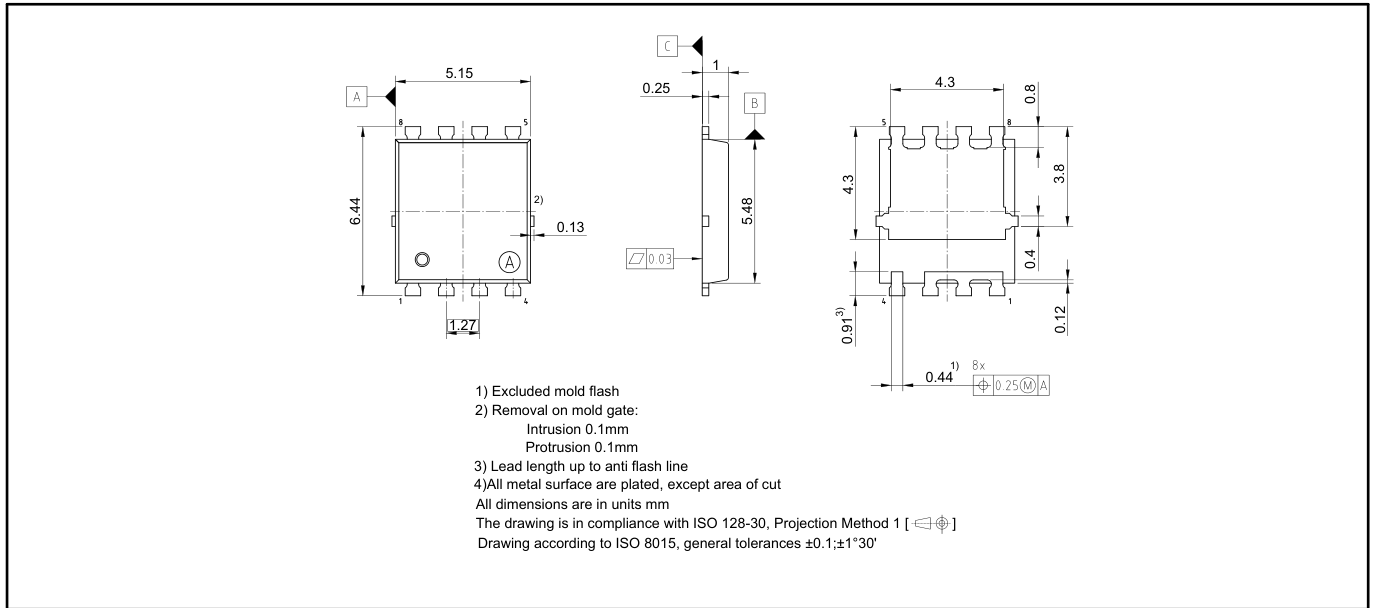
$V_{GS} = f(Q_{gate})$; $I_D = 75 \text{ A}$ pulsed; parameter: V_{DD}



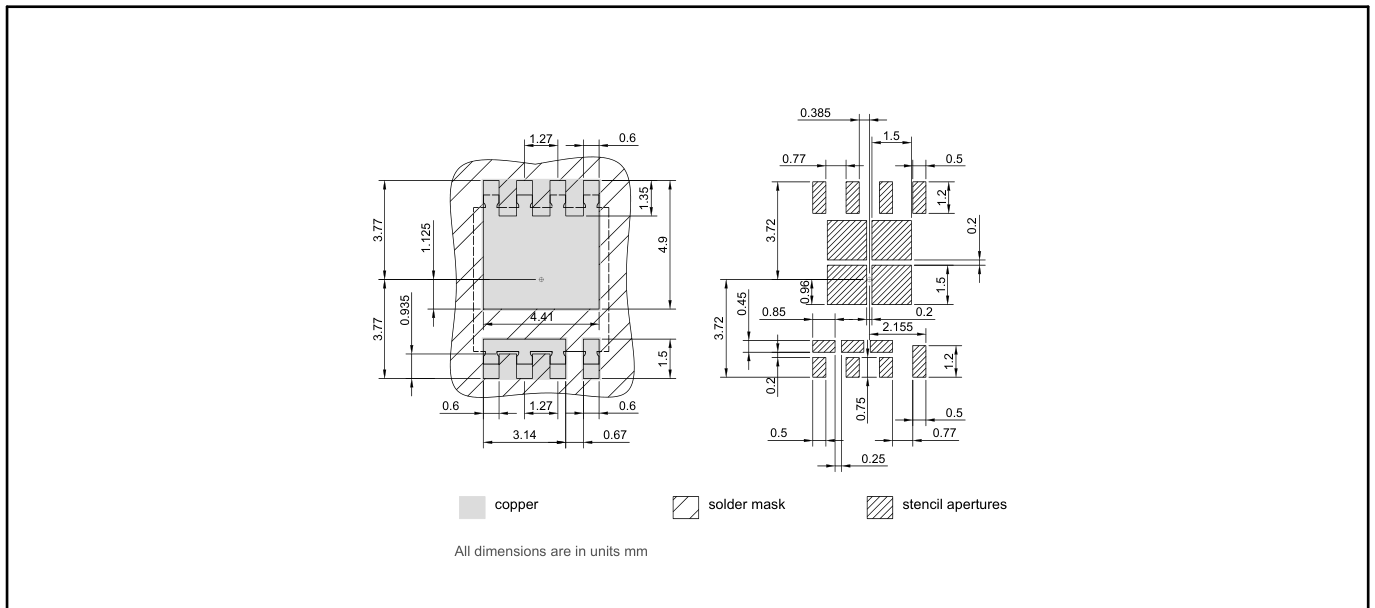
16 Gate charge waveforms



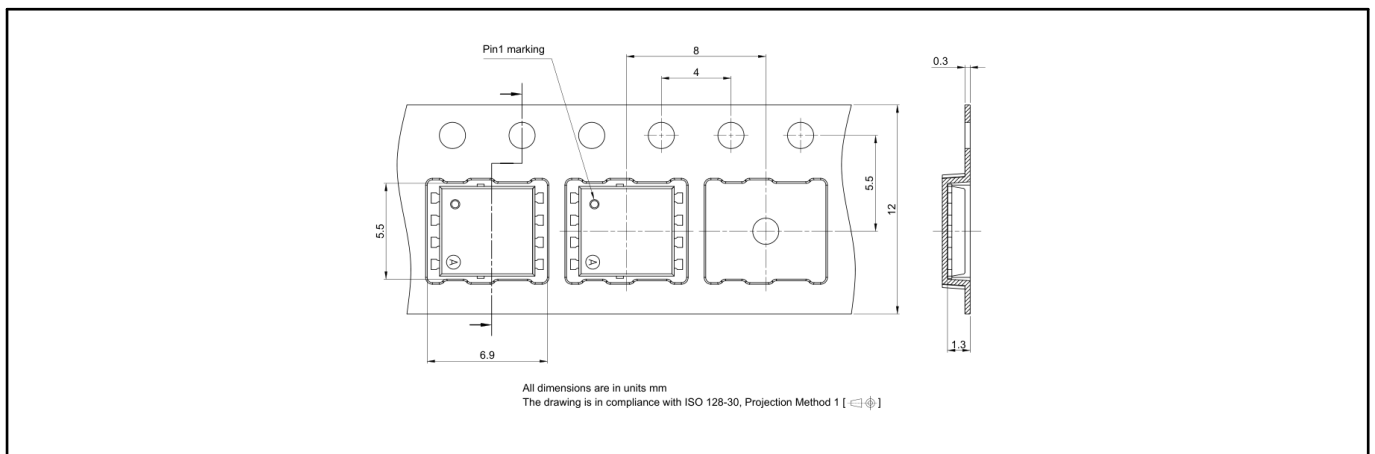
Package Outline



Footprint



Packaging





Revision History

Revision	Date	Changes
Revision 1.0	2024-09-17	Final Data Sheet

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Edition 2024-09-17

Published by

Infineon Technologies AG

81726 Munich, Germany

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Document reference

IAUCN08S7N024-Data-Sheet-10-Infineon

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